Northrop Grumman's Microelectronics Test Services

INTRODUCTION

Northrop Grumman's Microelectronics Center is known for creating mission-critical, defense solutions for products that perform in the most challenging environments. We are now proud to offer our US based, reliable and secure capabilities of post wafer design, build and test services, for your microelectronics from wafer to package form.

- Multi-Channel high frequency (up to W band)
- High connections on Digital, Mixed Signal, Cross Domain
- AOI (automated optical inspection) for all formats.
- Classified testing options
- Post Test Analysis Screening
- Test card, board, socket, etc., design
- Full suite of reliability and environmental testing
- Turnkey options available

RELIABILITY AND ENVIRONMENTAL TESTING

- RF shielded testing
- Burn-In / HAST / HTHB

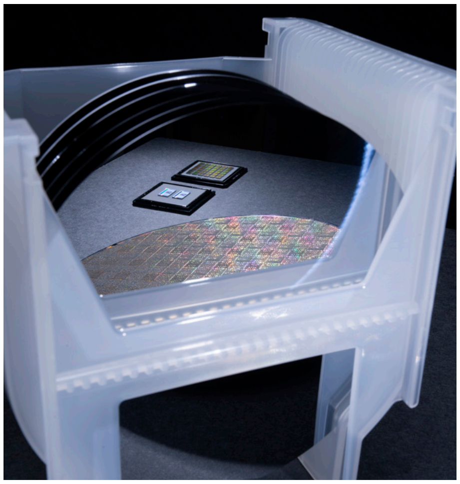
PRODUCT MANAGEMENT

- IP Protection Controls
- Yield Management Services

TEST DEVELOPMENT

- Hardware & Software Design
- RFIC/ASIC/Mixed Signal/ High Power Test Experience

Format	Temperature	Automated Inspection	Automated Handling
100 mm	Ambient, Hot	Yes	No
150 mm	Ambient, Hot		Yes
200 mm	Ambient, Hot		Yes
300 mm	Ambient, Hot		Yes
Film Frame	Ambient		Yes
Singulated	Ambient, Hot		No
Interposer	Ambient, Hot		Yes
Package	Cold, Ambient, Hot		Yes



www.ngc.com/what-we-do/microelectronics/

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